

规格书编号

SPEC NO :

产品规格书 SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: SAW FILTER
MODEL NO 型号: HDF63M SMD-24
MARKING 印字: HD BF06305A24
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ DATE 日期: 2011-9-5

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

1. SCOPE

This specification shall cover the characteristics of SAW filter 63MHz with used for remote-control security.

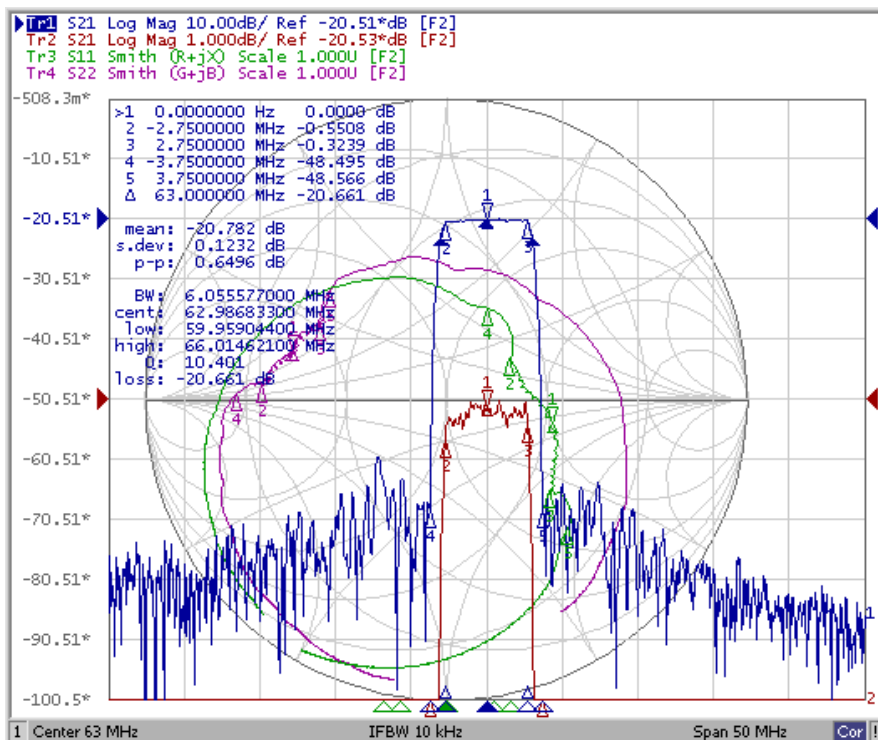
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +80°C
Storage temperature	-45°C to +85°C

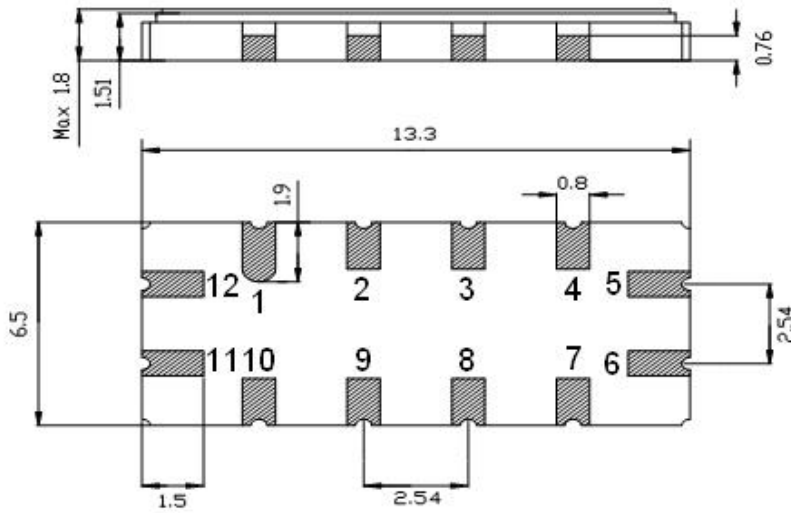
2-1. Electrical characteristics

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	63.0	-
Insertion Loss (60.25~65.75MHz)	dB		20.5	23.0
Amplitude Ripple (60.25~65.75MHz)	dB		0.5	1.2
Group delay ripple (60.25~65.75MHz)	ns		75	150
Relative Attenuation	dB			-
DC ~59.25 MHz		36	40	
66.75~100 MHz		38	40	
Input/Output Impedance	Ohms		50	

2-2. Typical frequency response

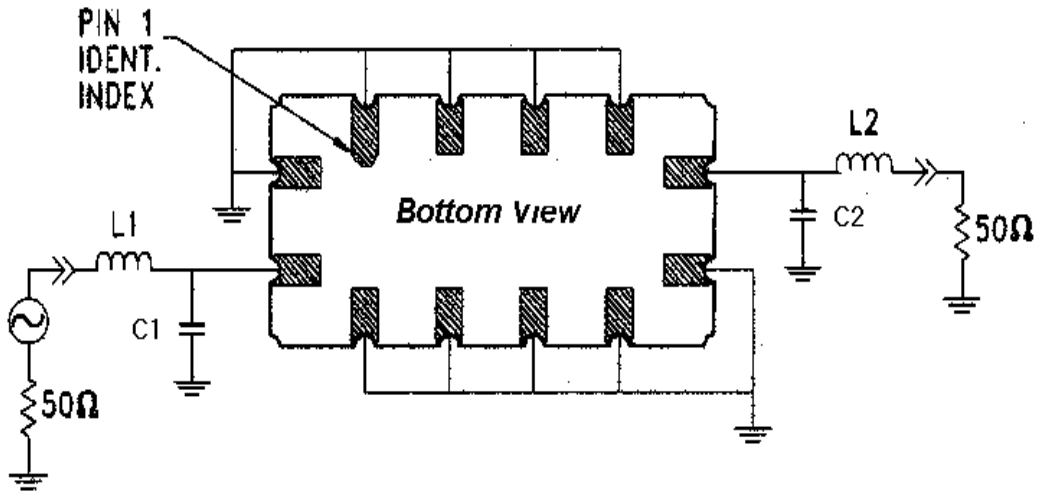


3. DIMENSION



All dimension tolerance <0.2mm

4. TEST CIRCUIT



L1=L2=220nH C1=75pF C2=43pF

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-1.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-1.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-1.

5-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-1.

6. REMARK**6.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.